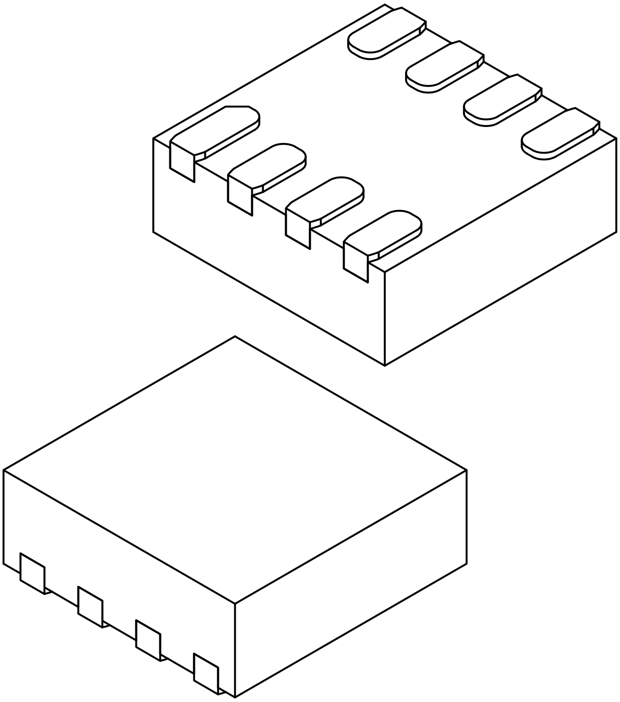
8-Lead Thin Dual Flatpack No-Lead (8HW) 2x2x0.8mm Body [TDFN] With Chip On Lead

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.70	0.75	0.80
Standoff	A1	0.00	-	0.05
Terminal Thickness	A3		0.20 REF	
Overall Length	D		2.00 BSC	
Overall Width	E		2.00 BSC	
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.40	0.50	0.60
Pin 1 Terminal Length	L1	0.50	0.60	0.70

Notes:

1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
2. The package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
   REF: Reference Dimension, usually without tolerance, is for information purposes only.